EPFL - CMi

FLX 2320-S

WARNING

Only the CMi Staff is qualified to do a service or to do maintenance

User manual

1. Login

1.1. Logon on the ACCESS CONTROL SYSTEM on the zone computer to unlock the keyboard of the FLX 2320-S

2. Starting up

- 2.1. "SOURCE" light must be already ON (tool powered up) . Orange light
- 2.2. "MAIN POWER": Breaker ON → . Green light .
- 2.3. "LASER" : Turn the key to ON → . Green light .

3. Loading

- 3.1. Open the door
- 3.2. Place the Locator Ring for 4" wafer positioning at a given angle
- **3.3.** Put your substrate on the substrate holder
- **3.4.** Close the door

4. Recipe Selection and Start Measurement

4.1. Start WINFLX, enter your login and password



Login User Name											
	Select User:	cmi	ок								
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	Password:		Exit								
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FLX © TOHO TECHNOLOGY

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EPFL-CMi/PhL						ad	Save		(

- 4.3. First measurement : no film : Measure / First (no film)
 - Enter File name (for example ID number of the wafer)
 - Enter ID for the first measurement (for example: 1 @ 0°; 2 @ 90°)
 - Thickness of the substrate can be adjusted if need be.



 WINFLX Windows Application[UserID : planglet]

 Measure
 Utilities

 Edit
 Analysis

 View
 Help

 First (no film)

 Single

 Time

 Temperature

 Exit

- 4.4. Perform your thin film deposition on upper side of your wafer
- 4.5. Stress measurement
 - 4.5.1. Select "Single" from the Measure tab on the main screen



- File : File name (for example ID number of the wafer)
- ID of the first measurement (for example: 1 @ 0° ; 2 @ 90°)
- Film thickness in Å

4.5.2. Press the "Measure" button. The instrument will perform a scan.

4.5.3. Results are then displayed: Intensity graph, Deflection graph with stress calculation.

5. Unloading

5.1. Open the door – Get back your substrate on the substrate holder – Close the door

6. Shutting down

- 6.1. "LASER" : Turn the key to OFF
- 6.2. "MAIN POWER": OFF
- 6.3. "SOURCE" light stays always ON (tool powered up) . Orange light .

7. Logout

- 7.1. Logout from the FLX 2320-S
- **7.2.** Logout from the ACCESS CONTROL SYSTEM.